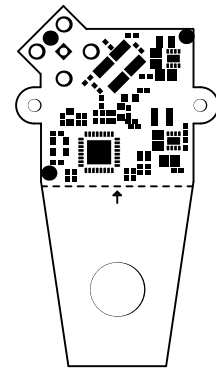
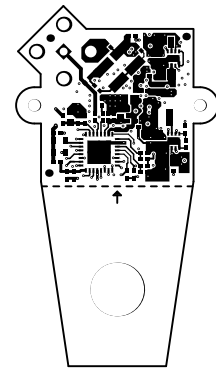


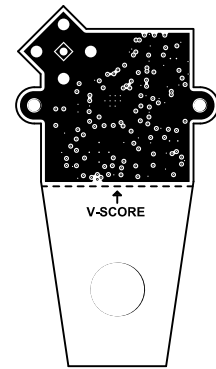
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01002	REV: E3	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: TIDA-01002		
PLOT NAME = Top Overlay	GENERATED : 2/27/2018 12:54:55 PM	TEXAS INSTRUMENTS	



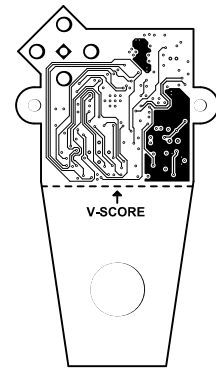
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01002	REV: E3	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: TIDA-01002		
PLOT NAME = Top Solder Mask	GENERATED : 2/27/2018 12:54:59 PM	TEXAS INSTRUMENTS	



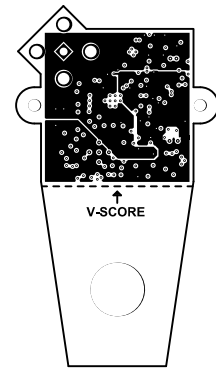
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01002	REV: E3	SUN REV: Not In VersionControl
LAYER NAME = Layer 1 - Top Layer	TID #: TIDA-01002		
PLOT NAME = Top Layer	GENERATED : 2/27/2018 12:55:03 PM	TEXAS INSTRUMENTS	



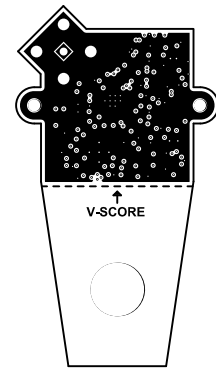
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01002	REV: E3	SUN REV: Not In VersionControl
LAYER NAME = <del>Board-001</del> <del>ONE</del>	TID #: TIDA-01002		
PLOT NAME = Ground Layer 2	GENERATED : 2/27/2018 12:55:06 PM	TEXAS INSTRUMENTS	



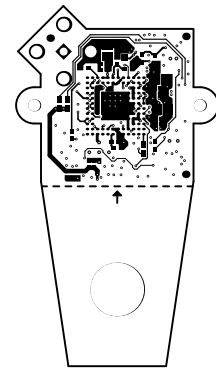
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01002	REV: E3	SUN REV: Not In VersionControl
LAYER NAME = <del>Board-Signal</del>	TID #: TIDA-01002		
PLOT NAME = Video, Control + 9V Layer 3	GENERATED : 2/27/2018 12:55:09 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01002	REV: E3	SUN REV: Not In VersionControl
LAYER NAME = <del>Board-Signal 2</del>	TID #: TIDA-01002		
PLOT NAME = Power Layer 4	GENERATED : 2/27/2018 12:55:13 PM	TEXAS INSTRUMENTS	

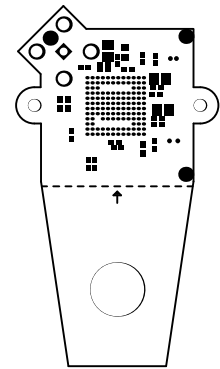


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01002	REV: E3	SUN REV: Not In VersionControl
LAYER NAME = <del>Board-001</del> Board-001	TID #: TIDA-01002		
PLOT NAME = Ground Layer 5	GENERATED : 2/27/2018 12:55:17 PM	TEXAS INSTRUMENTS	

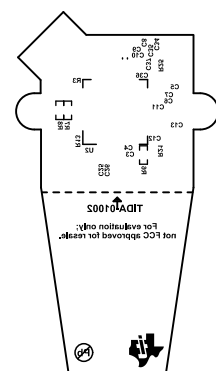


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01002	REV: E3	SUN REV: Not In VersionControl
LAYER NAME = Layer 6 - Bottom Layer	TID #: TIDA-01002		
PLOT NAME = Bottom Layer	GENERATED : 2/27/2018 12:55:20 PM		TEXAS INSTRUMENTS

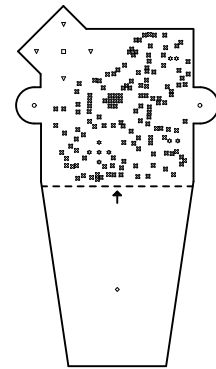




ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01002	REV: E3	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: TIDA-01002		
PLOT NAME = Bottom Solder Mask	GENERATED : 2/27/2018 12:55:22 PM	TEXAS INSTRUMENTS	

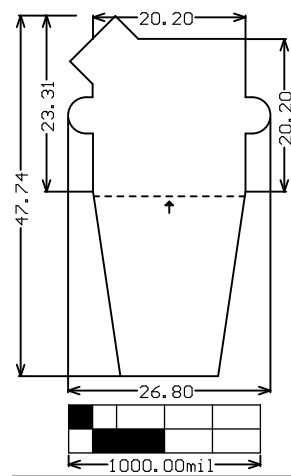


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01002	REV: E3	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: TIDA-01002		
PLOT NAME = Bottom Overlay	GENERATED : 2/27/2018 12:55:24 PM	TEXAS INSTRUMENTS	



Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
○	2	62.99mil (1.600mm)	NPTH	Round	Layer 1 - Top Layer - Layer 6 - Bottom Layer	
◇	1	280.00mil (7.112mm)	NPTH	Round	Layer 1 - Top Layer - Layer 6 - Bottom Layer	
⊗	137	6.00mil (0.152mm)	PTH	Round	Layer 1 - Top Layer - Layer 6 - Bottom Layer	
⊛	9	7.87mil (0.200mm)	PTH	Round	Layer 1 - Top Layer - Layer 6 - Bottom Layer	
□	1	41.34mil (1.050mm)	PTH	Round	Layer 1 - Top Layer - Layer 6 - Bottom Layer	
▽	4	61.02mil (1.550mm)	PTH	Round	Layer 1 - Top Layer - Layer 6 - Bottom Layer	
	154 Total					

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01002	REV: E3	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: TIDA-01002		
PLOT NAME = Drill Drawing	GENERATED : 2/27/2018	12:55:27 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01002	REV: E3	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: TIDA-01002		
PLOT NAME = Board Dimensions	GENERATED : 2/27/2018 12:55:33 PM	TEXAS INSTRUMENTS	

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